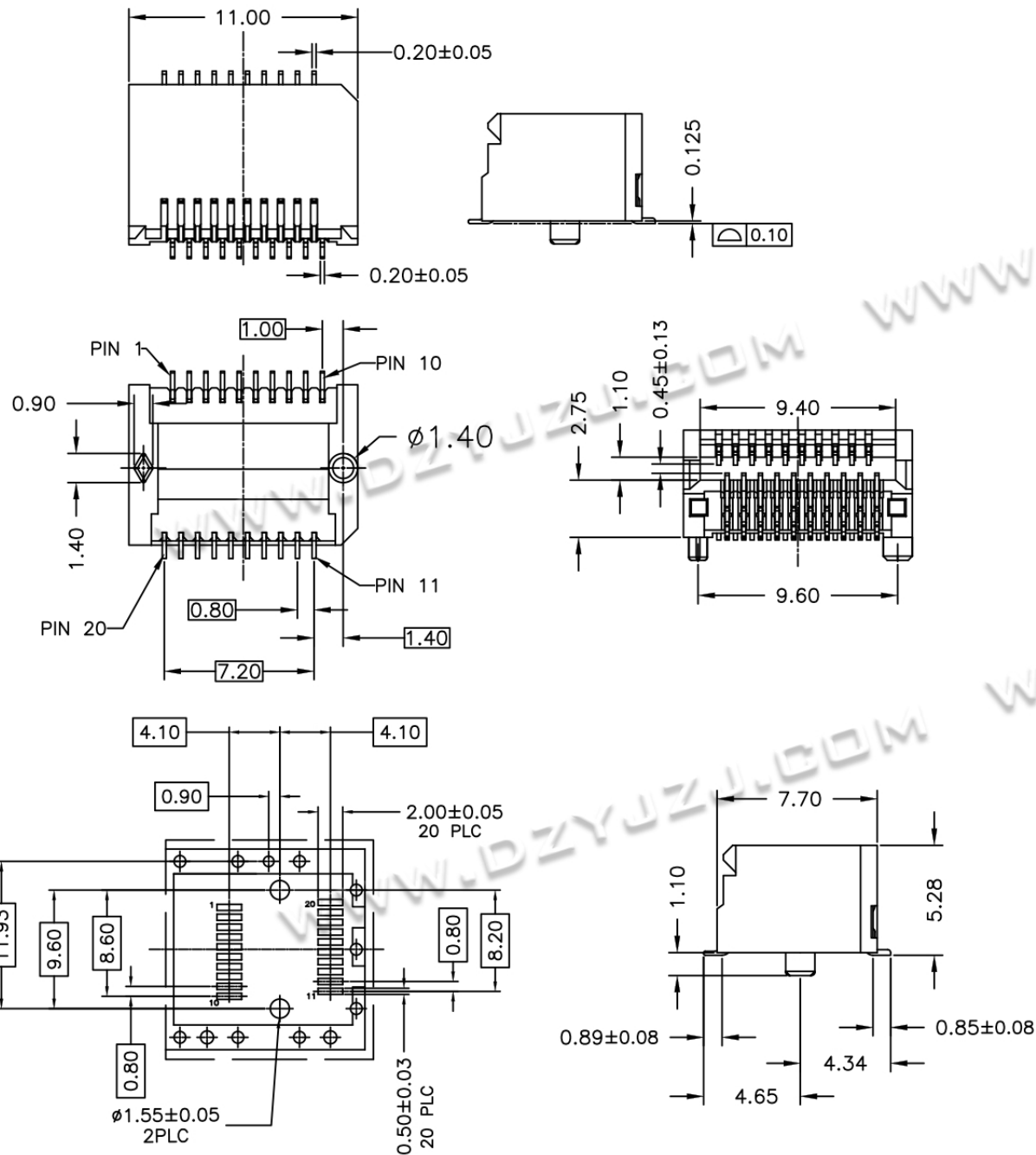




NOTES:

- 1.MATERIAL
HOUSING: HIGH TEMPERATURE LCP, Black, UL94 V-0.
- 2.CONTACTS: PHOSPHOR BRONZE
PLATING :15 μ " GOLD ON MATING AREA,
GOLD FLASH PLATING ON
SOLDER TAILS, 50 μ " NICKEL
UNDERPLATING OVERALL.
3. MECHANICAL REQUIREMENT:
3.1 DURABILITY:100 CYCLES MIN.
3.2 INSERTION AND EXTRACTION FORCE:40N MAX. & 11.5N MAX.
4. ENVIRONMENTAL:
4.1 CONTACT RESISTANCE:20 MILLIOHMS MAX INITIAL.
4.2 DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.
4.3 CURRENT RATING: 0.5 Amps Max.
4.4 OPERATION: -40°C TO +95°C
4.5 STORAGE: -55°C TO +105°C
4.6 REFLOW SOLDERING TEMPERATURE: 255~265° MAXIMUM
FOR 5~10 SECONDS.
4.9 ROHS COMPLIANT
- 5.PACKAGING: TAPE AND REEL



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TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15
X.' ±2' X.X' ±0.5'

UNIT: mm [inch]
SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

SFP 20PIN 0.8MM SMT

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC02-08SFP-053

MOLD NO.

APPROVED BY:

邱敏

DATE :

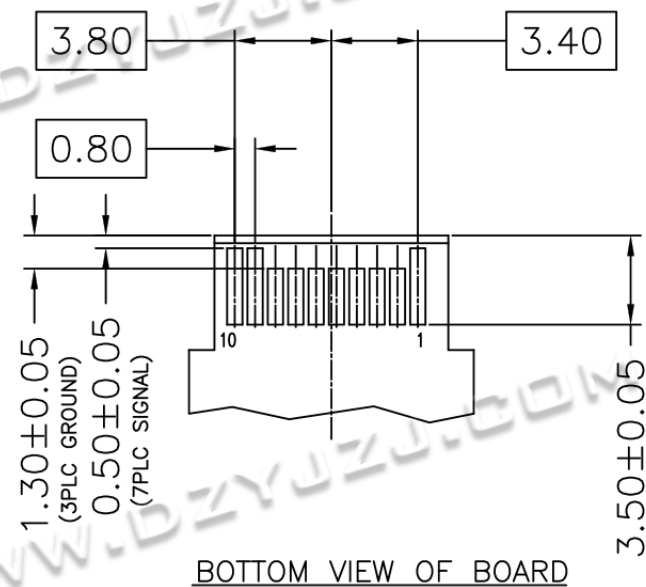
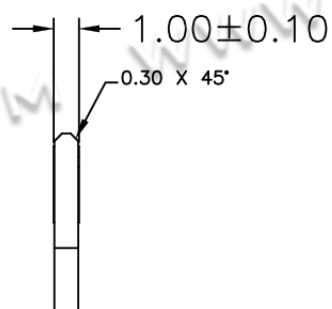
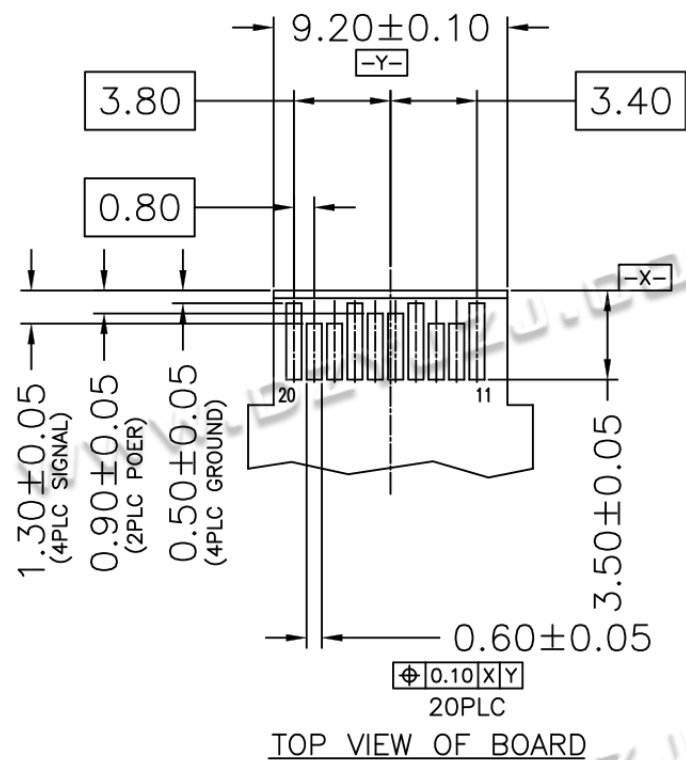
2014-02-23

DRAW NO:

HYC-2401251231

SHEET NO.

1 OF 1



RECOMMENDED LAYOUT DETAIL MATING TRANSCEIVER PCB



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SFP 20PIN 0.8MM SMT
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC02-08SFP-053
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2401251231
			SHEET NO. 1 OF 1